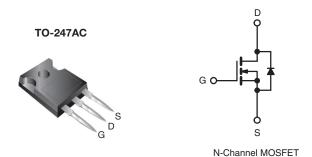


## **Power MOSFET**

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	60				
R <sub>DS(on)</sub> (Ω)	V <sub>GS</sub> = 10 V 0.014				
Q <sub>g</sub> (Max.) (nC)	160				
Q <sub>gs</sub> (nC)	48				
Q <sub>gd</sub> (nC)	54				
Configuration	Single				



#### **FEATURES**

- Dynamic dV/dt Rating
- Isolated Central Mounting Hole
- 175 °C Operating Temperature
- Fast Switching
- · Ease of Paralleling
- Simple Drive Requirements
- Compliant to RoHS Directive 2002/95/EC



#### **DESCRIPTION**

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-247AC package is preferred for commercial-industrial applications where higher power levels preclude the use of TO-220AB devices. The TO-247AC is similar but superior to the earlier TO-218 package because of its isolated mouting hole. It also provides greater creepage distance between pins to meet the requirements of most safety specifications.

ORDERING INFORMATION			
Package	TO-247AC		
Lead (Pb)-free	IRFP054PbF		
Lead (FD)-liee	SiHFP054-E3		
SnPb	IRFP054		
SIFD	SiHFP054		

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V <sub>DS</sub>	60	V	
Gate-Source Voltage			$V_{GS}$	± 20	V	
Continuous Drain Currente				70		
Continuous Drain Current	$V_{GS}$ at 10 V $T_{C} = 23 \text{ C}$		I <sub>D</sub>	64	Α	
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	360	1	
Linear Derating Factor				1.5	W/°C	
Single Pulse Avalanche Energy <sup>b</sup>			E <sub>AS</sub>	373	mJ	
Maximum Power Dissipation T <sub>C</sub> = 25 °C			$P_{D}$	230	W	
Peak Diode Recovery dV/dt <sup>c</sup>			dV/dt	4.5	V/ns	
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C	
Soldering Recommendations (Peak Temperature) <sup>d</sup>	s (Peak Temperature) <sup>d</sup> for 10 s			300		
Mounting Torque	6-32 or M3 screw			10	lbf ⋅ in	
Mounting Torque				1.1	N⋅m	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b.  $V_{DD}$  = 25 V, starting  $T_J$  = 25 °C, L = 92  $\mu$ H,  $R_\alpha$  = 25  $\Omega$ ,  $I_{AS}$  = 90 A (see fig. 12).
- c.  $I_{SD} \le 90$  A,  $dI/dt \le 200$  A/µs,  $V_{DD} \le V_{DS}$ ,  $T_J \le 175$  °C.
- d. 1.6 mm from case.
- e. Current limited by the package, (die current = 90 A).

<sup>\*</sup> Pb containing terminations are not RoHS compliant, exemptions may apply



THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	40		
Case-to-Sink, Flat, Greased Surface	R <sub>thCS</sub>	0.24	-	°C/W	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	0.65		

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static					•	•	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0$	V, I <sub>D</sub> = 250 μA	60	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference t	o 25 °C, I <sub>D</sub> = 1 mA	-	0.056	-	V/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_0$	<sub>GS</sub> , I <sub>D</sub> = 250 μA	2.0	-	4.0	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>G</sub> s	<sub>S</sub> = ± 20 V	-	-	± 100	nA
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 6	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V		-	25	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 48 \text{ V}, V_{C}$	<sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C	-	-	250	μA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 54 A <sup>b</sup>	-	-	0.014	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = 2	5 V, I <sub>D</sub> = 54 A <sup>b</sup>	25	-	-	S
Dynamic							
Input Capacitance	C <sub>iss</sub>	V	<sub>GS</sub> = 0 V,	-	4500	-	pF
Output Capacitance	C <sub>oss</sub>	V <sub>D</sub>	$p_{S} = 25 \text{ V},$	-	2000	-	
Reverse Transfer Capacitance	C <sub>rss</sub>	t = 1.0 ľ	MHz, see fig. 5	-	300	-	
Total Gate Charge	$Q_g$	V <sub>GS</sub> = 10 V		-	-	160	nC
Gate-Source Charge	$Q_{gs}$			-	-	48	
Gate-Drain Charge	$Q_{gd}$			-	-	54	
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{DD} = 30 \text{ V}, \ I_D = 64 \text{ A} \ ,$ $R_g = 6.2 \ \Omega, \ R_D = 0.45 \ \Omega, \ \text{see fig. } 10^b$		-	20	-	- ns
Rise Time	t <sub>r</sub>			-	160	-	
Turn-Off Delay Time	t <sub>d(off)</sub>			-	83	-	
Fall Time	t <sub>f</sub>			-	150	-	
Internal Drain Inductance	$L_D$	Between lead, 6 mm (0.25") from package and center of die contact		-	5.0	-	
Internal Source Inductance	L <sub>S</sub>			-	13	-	- nH
Drain-Source Body Diode Characteristic	s				•	,	
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	70	
Pulsed Diode Forward Current <sup>a</sup>	I <sub>SM</sub>			-	-	360	A
Body Diode Voltage	$V_{SD}$	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 90 A, V <sub>GS</sub> = 0 V <sup>b</sup>		-	-	2.5	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	$T_{J} = 25 \text{ °C}, I_{F} = 6.4 \text{ A}, dI/dt = 100 \text{ A/}\mu\text{s}^{b}$		-	270	540	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			-	1.1	2.2	μC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-		-on is do	minated b	y L <sub>S</sub> and	L <sub>D</sub> )

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width  $\leq 300~\mu s;$  duty cycle  $\leq 2~\%.$





## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

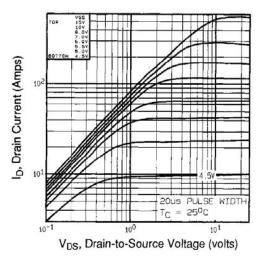


Fig. 1 - Typical Output Characteristics, T<sub>C</sub> = 25 °C

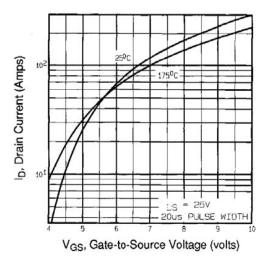


Fig. 3 - Typical Transfer Characteristics

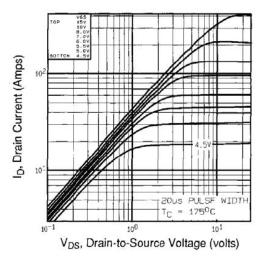


Fig. 2 - Typical Output Characteristics, T<sub>C</sub> = 175 °C

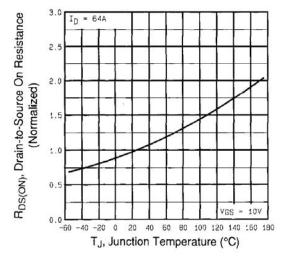


Fig. 4 - Normalized On-Resistance vs. Temperature



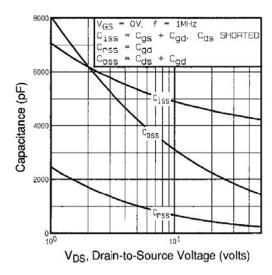


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

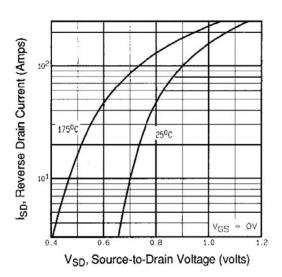


Fig. 7 - Typical Source-Drain Diode Forward Voltage

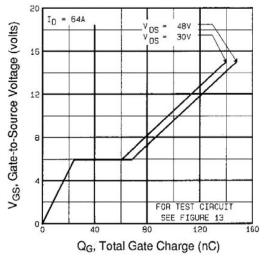


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

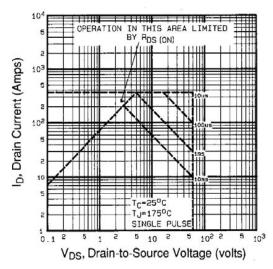


Fig. 8 - Maximum Safe Operating Area



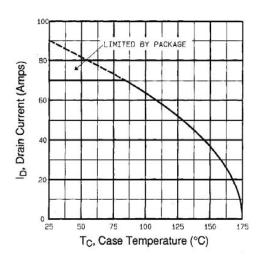


Fig. 9 - Maximum Drain Current vs. Case Temperature

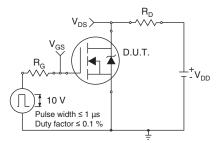


Fig. 10a - Switching Time Test Circuit

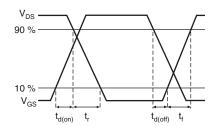


Fig. 10b - Switching Time Waveforms

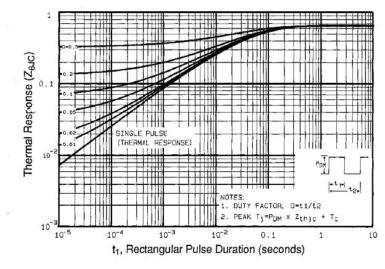


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



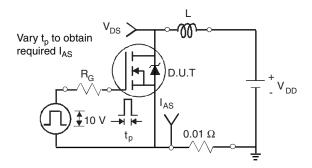


Fig. 12a - Unclamped Inductive Test Circuit

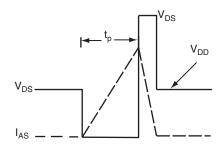


Fig. 12b - Unclamped Inductive Waveforms

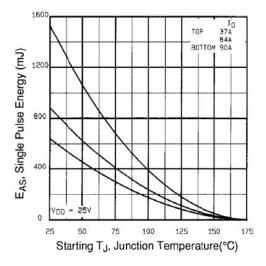


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

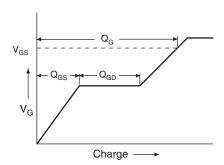


Fig. 13a - Basic Gate Charge Waveform

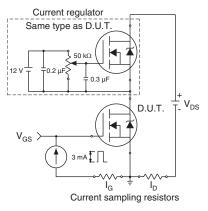
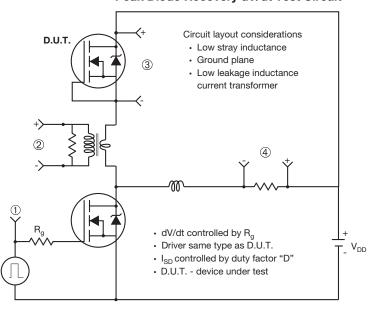


Fig. 13b - Gate Charge Test Circuit



### Peak Diode Recovery dV/dt Test Circuit



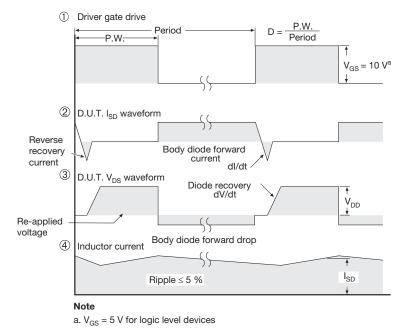


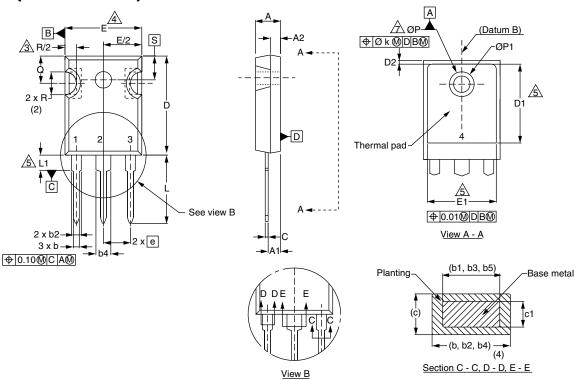
Fig. 14 - For N-Channel

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## **TO-247AC (HIGH VOLTAGE)**



	MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
Α	4.65	5.31	0.183	0.209
A1	2.21	2.59	0.087	0.102
A2	1.50	2.49	0.059	0.098
b	0.99	1.40	0.039	0.055
b1	0.99	1.35	0.039	0.053
b2	1.65	2.39	0.065	0.094
b3	1.65	2.37	0.065	0.093
b4	2.59	3.43	0.102	0.135
b5	2.59	3.38	0.102	0.133
С	0.38	0.86	0.015	0.034
c1	0.38	0.76	0.015	0.030
D	19.71	20.70	0.776	0.815
D1	13.08	-	0.515	-

	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
D2	0.51	1.30	0.020	0.051
Е	15.29	15.87	0.602	0.625
E1	13.72	-	0.540	-
е	5.46	BSC	0.215 BSC	
Øk	0.254		0.010	
L	14.20	16.10	0.559	0.634
L1	3.71	4.29	0.146	0.169
N	7.62	7.62 BSC		
ØΡ	3.56	3.66	0.140	0.144
Ø P1	-	7.39	-	0.291
Q	5.31	5.69	0.209	0.224
R	4.52	5.49	0.178	0.216
S	5.51 BSC		0.217 BSC	

ECN: S-81920-Rev. A, 15-Sep-08

DWG: 5971

## Notes

- 1. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 2. Contour of slot optional.
- 3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body.
- 4. Thermal pad contour optional with dimensions D1 and E1.
- 5. Lead finish uncontrolled in L1.
- 6. Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154").
- 7. Outline conforms to JEDEC outline TO-247 with exception of dimension c.

Document Number: 91360
Revision: 15-Sep-08
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